



STB80PF55 STP80PF55

P-channel 55 V, 0.016 Ω , 80 A TO-220, D²PAK
STripFET™ II Power MOSFET

Features

Type	V _{DSS}	R _{DS(on)}	I _D
STP80PF55	55V	<0.018 Ω	80A
STB80PF55	55V	<0.018 Ω	80A

- Extremely dv/dt capability
- 100% avalanche tested
- Application oriented characterization

Application

- Switching applications

Description

These Power MOSFETs are the latest development of STMicroelectronics unique "single feature size" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps allowing remarkable manufacturing reproducibility.

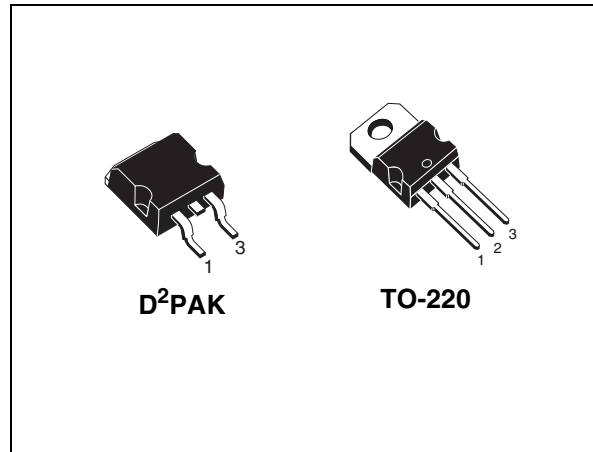


Figure 1. Internal schematic diagram

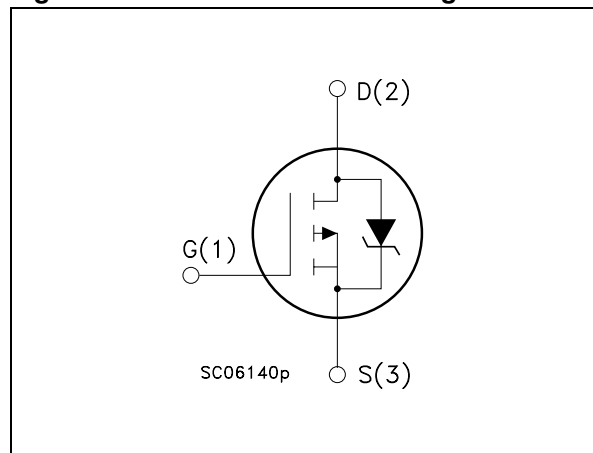


Table 1. Device summary

Order code	Marking	Package	Packaging
STP80PF55	P80PF55	TO-220	Tube
STB80PF55	B80PF55	D ² PAK	Tape and reel

Contents

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1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage ($V_{GS} = 0$)	55	V
V_{GS}	Gate-source voltage	± 16	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	80	A
I_D	Drain current (continuous) at $T_C = 100^\circ\text{C}$	57	A
$I_{DM}^{(2)}$	Drain current (pulsed)	320	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	300	W
	Derating factor	2	W/ $^\circ\text{C}$
$dv/dt^{(3)}$	Peak diode recovery voltage slope	7	V/ns
$E_{AS}^{(4)}$	Single pulse avalanche energy	1.4	J
T_j	Operating junction temperature	-55 to 175	$^\circ\text{C}$
T_{stg}	Storage temperature		

1. Current limited by package.
2. Pulse width limited by safe operating area .
3. $I_{SD} \leq 40\text{A}$, $di/dt \leq 300\text{ A}/\mu\text{s}$, $V_{DD} = 80\% V_{(BR)DSS}$.
4. Starting $T_j = 25^\circ\text{C}$, $I_D = 80\text{A}$, $V_{DD} = 40\text{V}$.

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	0.5	$^\circ\text{C}/\text{W}$
R_{thj-a}	Thermal resistance junction-ambient max	62.5	$^\circ\text{C}/\text{W}$
T_l	Maximum lead temperature for soldering purpose	300	$^\circ\text{C}$

Note: For the P-CHANNEL MOSFET actual polarity of voltages and current has to be reversed

2 Electrical characteristics

($T_{CASE}=25^{\circ}C$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250 \text{ mA}, V_{GS} = 0$	55			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating}, T_C=125^{\circ}C$			1 10	μA μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 16 \text{ V}$			± 10	μA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2	3	4	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 40 \text{ A}$		0.016	0.018	Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
g_{fs}	Forward transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max},$ $I_D = 40 \text{ A}$	-	32		S
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25 \text{ V}, f = 1\text{MHz},$ $V_{GS} = 0$	-	5500 1130 600		pF pF pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	$I_D = 25 \text{ A}, V_{DD} = 80 \text{ V},$ $V_{GS} = 10 \text{ V}$ <i>(see Figure 15)</i>	-	190 27 65	258	nC nC nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on delay time Rise time	$V_{DD}=25 \text{ V}, I_D=40 \text{ A},$ $R_G=4.7 \Omega, V_{GS}=10 \text{ V}$ <i>(see Figure 14)</i>	-	35 190	-	ns ns
$t_{d(off)}$ t_f	Turn-off delay time Fall time	$V_{DD}=25 \text{ V}, I_D=40 \text{ A},$ $R_G=4.7 \Omega, V_{GS}=10 \text{ V}$ <i>(see Figure 14)</i>	-	165 80	-	ns ns
$t_{r(Voff)}$ t_f t_c	Off-voltage rise time Fall time Cross-over time	$V_{clamp}=40 \text{ V}, I_D=80 \text{ A},$ $R_G=4.7 \Omega, V_{GS}=10 \text{ V}$ <i>(see Figure 14)</i>	-	60 40 85	-	ns ns ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		10	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		40	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 80 \text{ A}, V_{GS} = 0$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 80 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 25 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$	-	110		ns
Q_{rr}	Reverse recovery charge			495		μC
I_{RRM}	Reverse recovery current			9		A

1. Pulse width limited by T_{jmax} .

2. Pulsed: pulse duration = 300 μs , duty cycle 1.5 %.

Note: For the P-CHANNEL MOSFET actual polarity of voltages and current has to be reversed

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for TO-220 and D²PAK

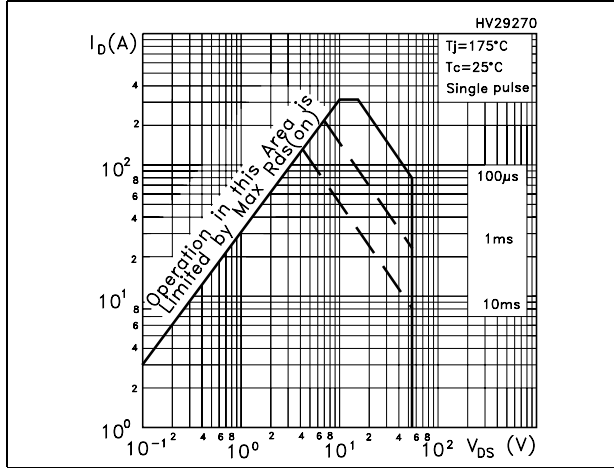


Figure 3. Thermal impedance for TO-220 and D²PAK

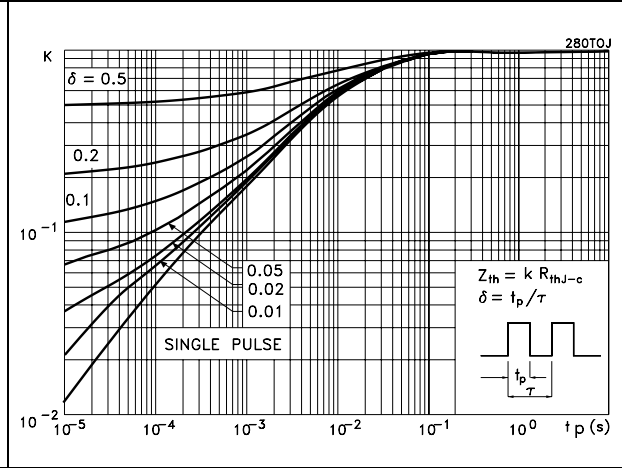


Figure 4. Output characteristics

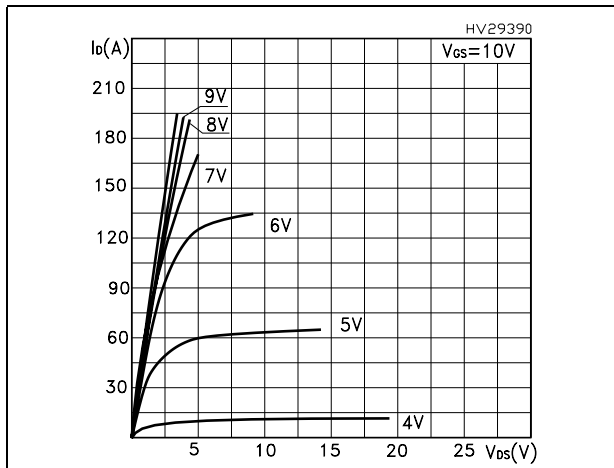


Figure 5. Transfer characteristics

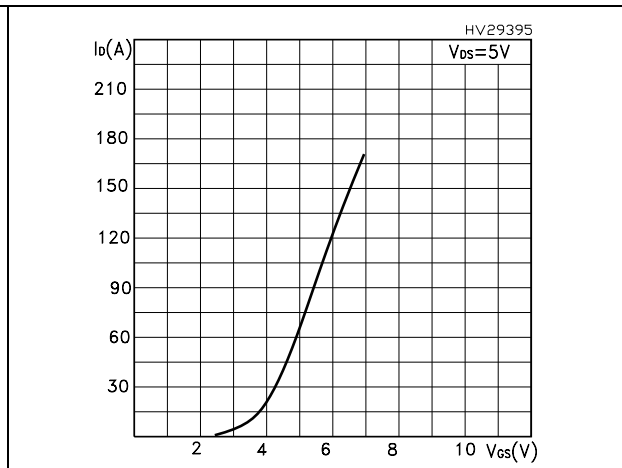


Figure 6. Transconductance

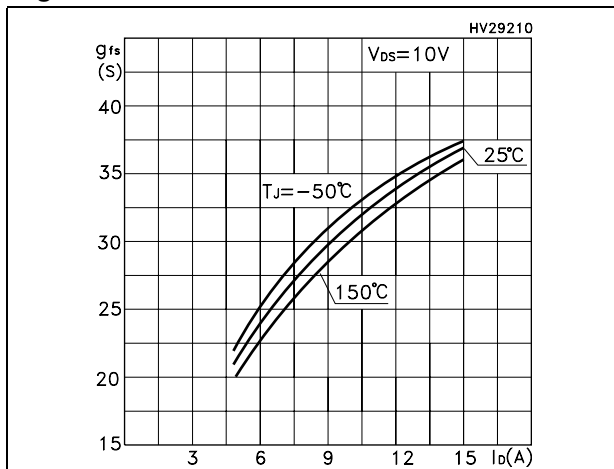


Figure 7. Static drain-source on resistance

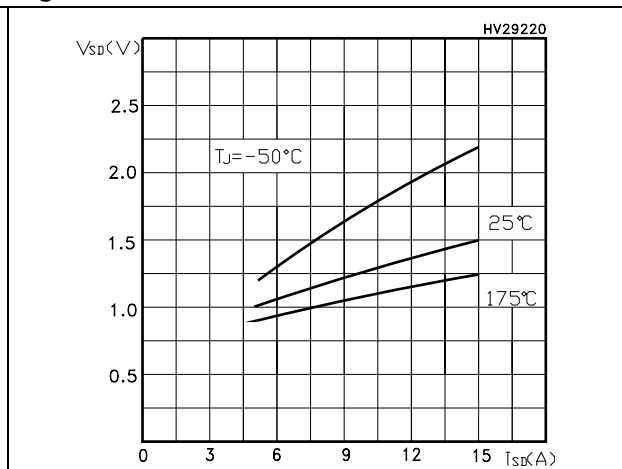


Figure 8. Gate charge vs gate-source voltage Figure 9. Capacitance variations

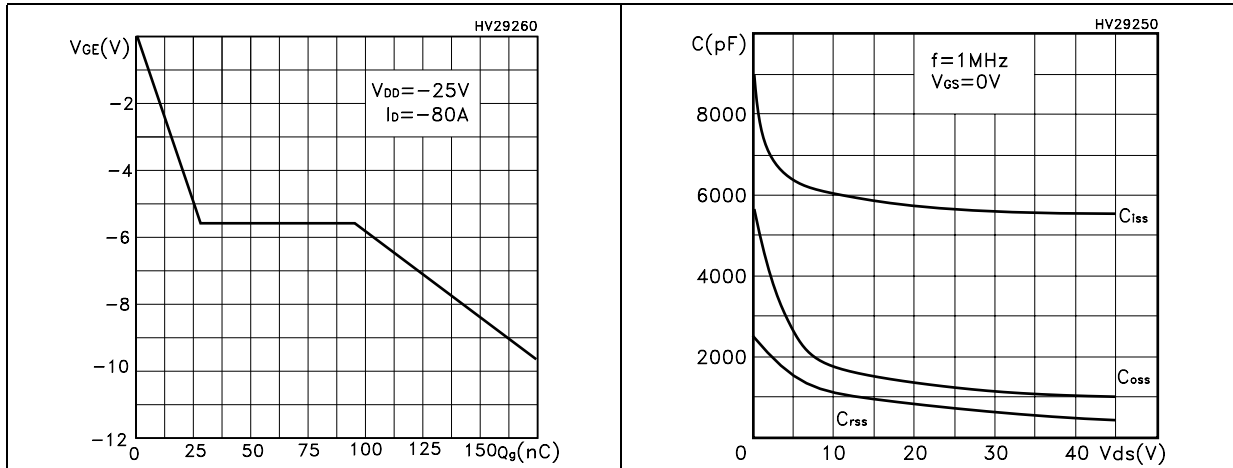


Figure 10. Normalized gate threshold voltage vs temperature Figure 11. Normalized on resistance vs temperature

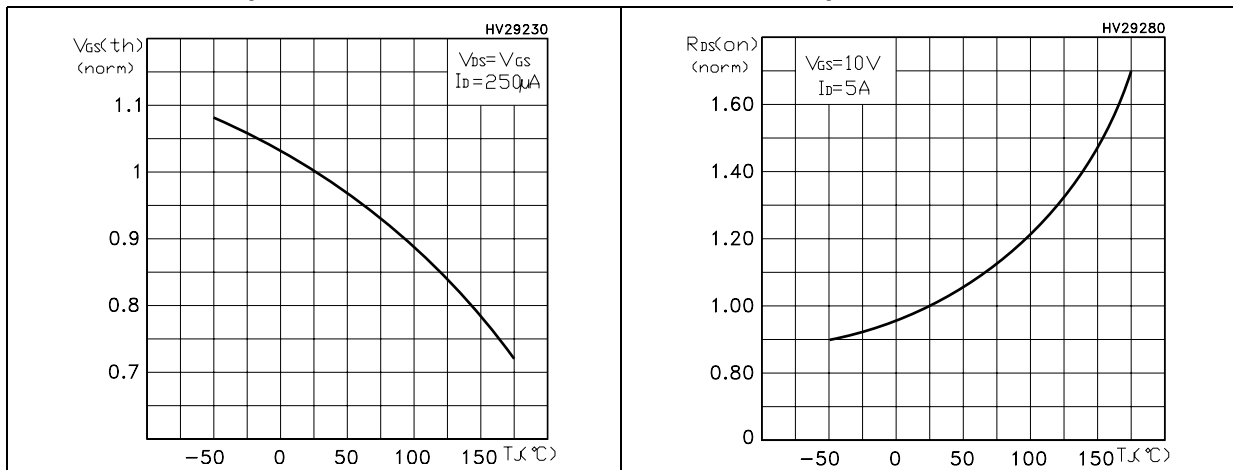
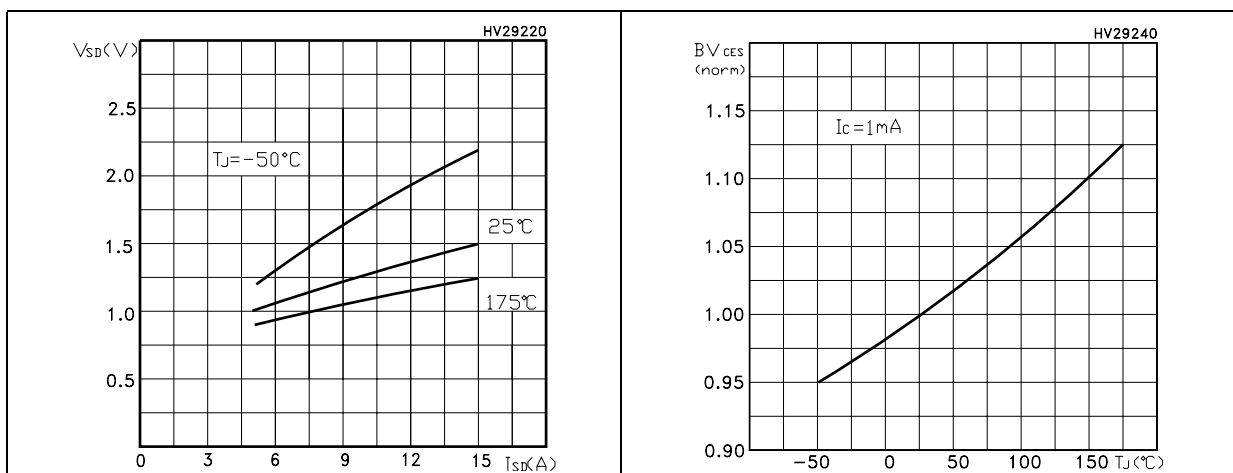


Figure 12. Source-drain diode forward characteristics Figure 13. Normalized BV_{DSS} vs temperature



3 Test circuits

Figure 14. Switching times test circuit for resistive load

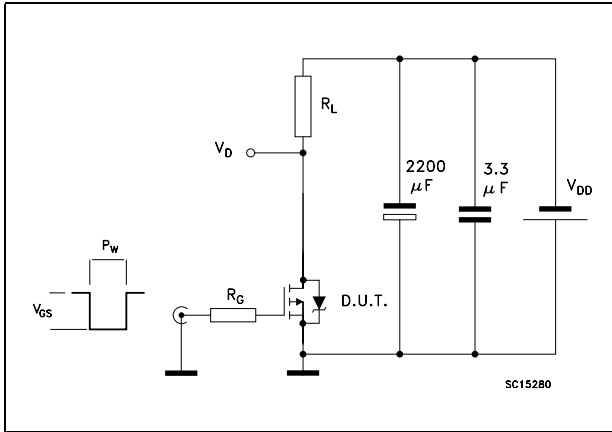


Figure 15. Gate charge test circuit

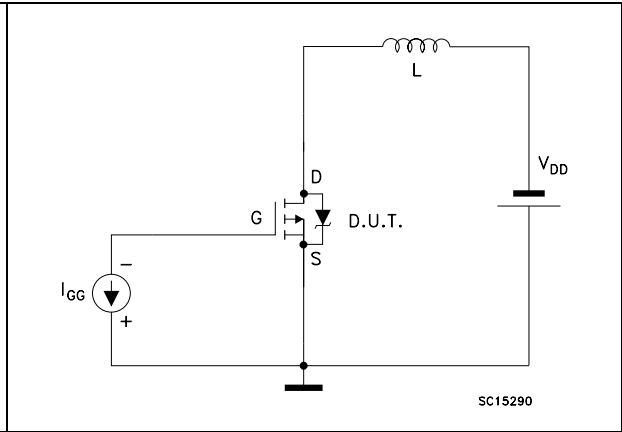
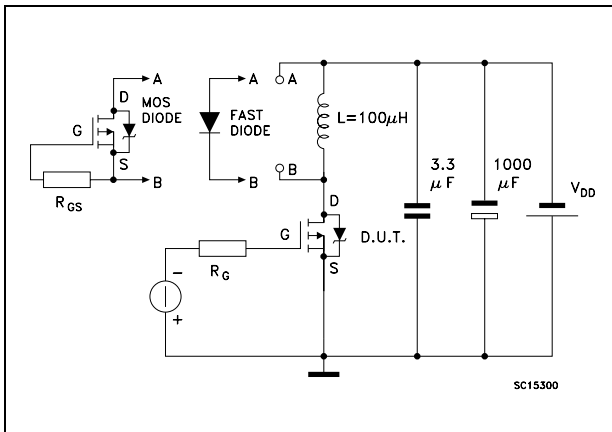


Figure 16. Test circuit for inductive load switching and diode recovery times



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 8. D²PAK mechanical data

Dim	mm			inch		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
A1	0.03		0.23	0.001		0.009
b	0.70		0.93	0.027		0.037
b2	1.14		1.70	0.045		0.067
c	0.45		0.60	0.017		0.024
c2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1	7.50			0.295		
E	10		10.40	0.394		0.409
E1	8.50			0.334		
e		2.54			0.1	
e1	4.88		5.28	0.192		0.208
H	15		15.85	0.590		0.624
J1	2.49		2.69	0.099		0.106
L	2.29		2.79	0.090		0.110
L1	1.27		1.40	0.05		0.055
L2	1.30		1.75	0.051		0.069
R		0.4			0.016	
V2	0°		8°	0°		8°

Figure 17. D²PAK drawing

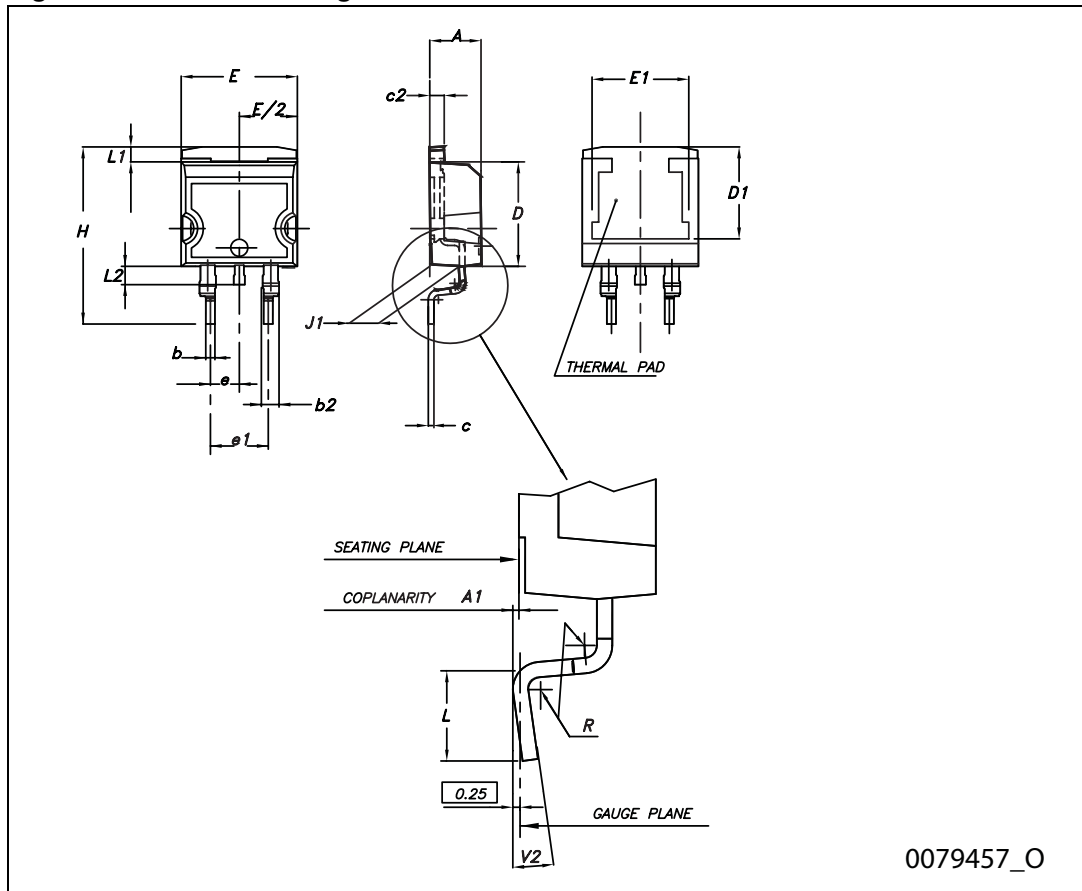
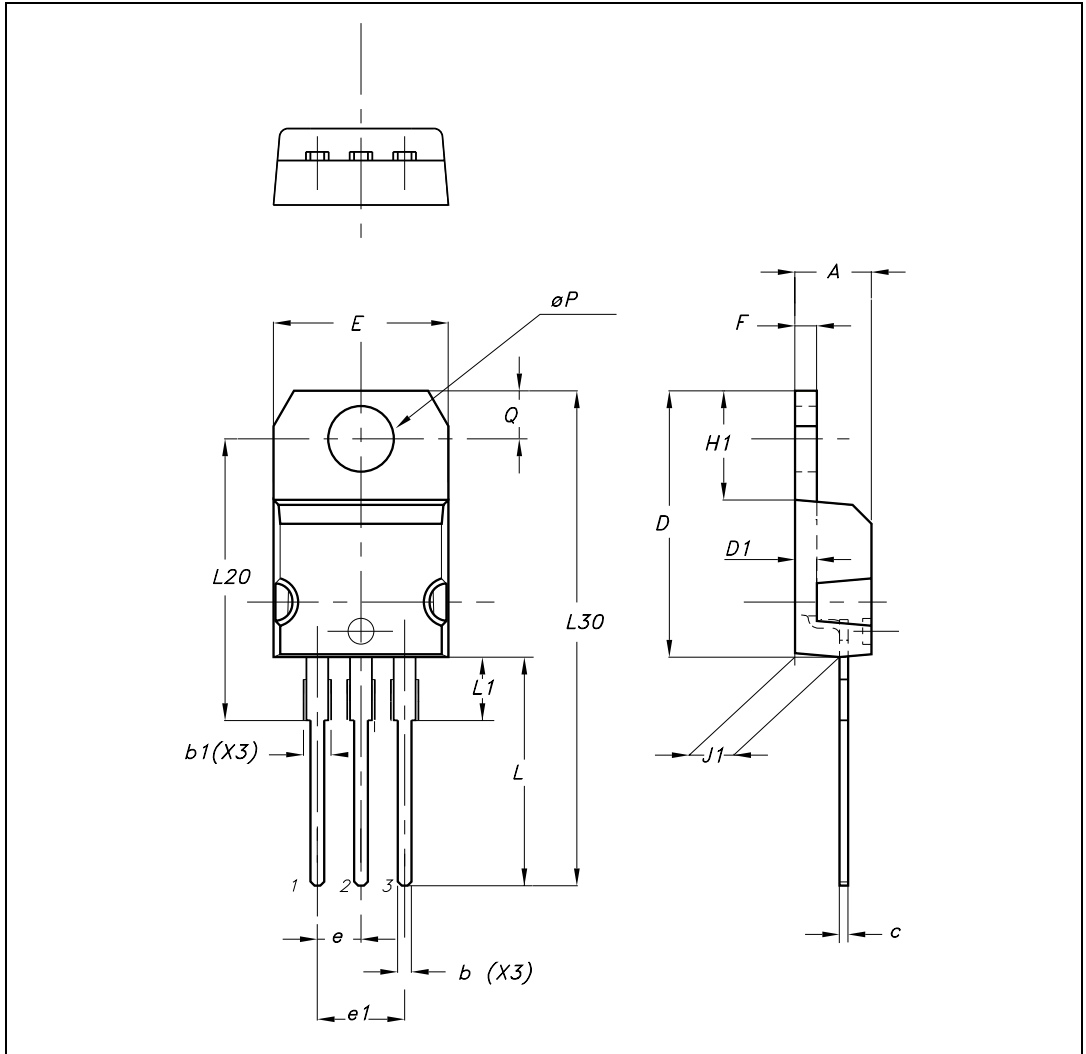


Table 9. TO-220 mechanical data

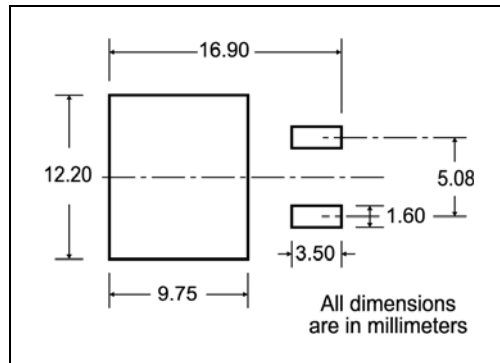
Dim	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

Figure 18. TO-220 drawing



5 Packaging mechanical data

D²PAK FOOTPRINT



TAPE AND REEL SHIPMENT

40 mm min. Access hole at slot location

Full radius

Tape slot in core for tape start

2.5mm min. width

REEL MECHANICAL DATA

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A		330		12.992
B	1.5		0.059	
C	12.8	13.2	0.504	0.520
D	20.2		0.795	
G	24.4	26.4	0.960	1.039
N	100		3.937	
T		30.4		1.197

BASE QTY	BULK QTY
1000	1000

TAPE MECHANICAL DATA

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A0	10.5	10.7	0.413	0.421
B0	15.7	15.9	0.618	0.626
D	1.5	1.6	0.059	0.063
D1	1.59	1.61	0.062	0.063
E	1.65	1.85	0.065	0.073
F	11.4	11.6	0.449	0.456
K0	4.8	5.0	0.189	0.197
P0	3.9	4.1	0.153	0.161
P1	11.9	12.1	0.468	0.476
P2	1.9	2.1	0.075	0.082
R	50		1.574	
T	0.25	0.35	0.0098	0.0137
W	23.7	24.3	0.933	0.956

10 pitches cumulative tolerance on tape +/- 0.2 mm

Center line of cavity

User Direction of Feed

FEED DIRECTION

Bending radius R min.

* on sales type

6 Revision history

Table 10. Document revision history

Date	Revision	Changes
09-Sep-2004	4	Revalidation
12-Sep-2006	5	New template, D ² PAK added
09-Aug-2010	6	Content reworked to improve readability, no technical changes.

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